

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PK}	75	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	5	A
ESD per IEC 61000-4-2 (Air) ⁽¹⁾ ESD per IEC 61000-4-2 (Contact) ⁽¹⁾	V_{ESD}	± 30 ± 25	kV
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics ($T = 25^\circ C$ unless otherwise specified)

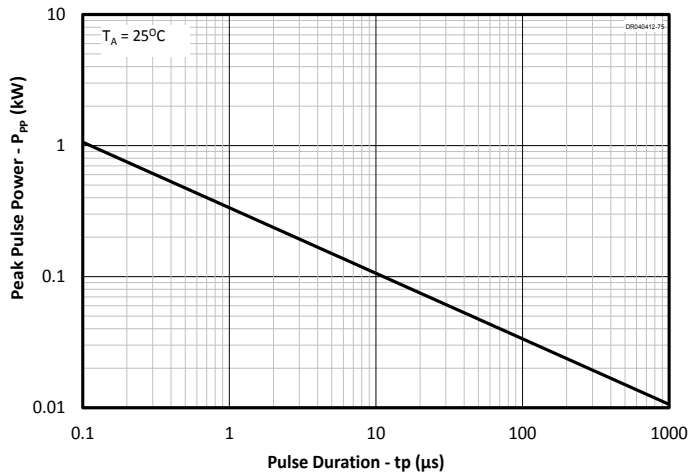
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}	Any I/O to GND			5	V
Reverse Breakdown Voltage	V_{BR}	$I_{BR} = 1mA$, Any I/O to GND	6.5	9	11	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V$, Any I/O to GND		5	100	nA
Clamping Voltage	V_C	$t_p = 8/20\mu s$ Any I/O to GND	$I_{PP} = 1A$		12	V
			$I_{PP} = 5A$		15	
ESD Clamping Voltage ²	V_C	$t_p = 0.2/100ns$ Any I/O to GND	$I_{TLP} = 4A$	11		V
			$I_{TLP} = 16A$	17		
Dynamic Resistance ^{2,3}	R_{DYN}	$t_p = 0.2/100ns$		0.5		Ω
Junction Capacitance	C_J	$V_R = 0V$, $f = 1MHz$	Any I/O to GND	0.5	0.6	pF
			Between I/O pins	0.25	0.4	

Notes

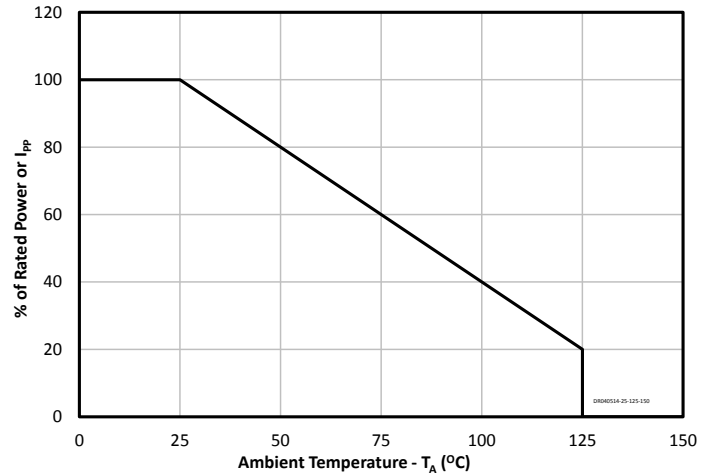
- 1) Measured with a 20dB attenuator, 50 Ohm scope input impedance, 2GHz bandwidth. ESD gun return path connected to ESD ground plane.
- 2) Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.
- 3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

Typical Characteristics

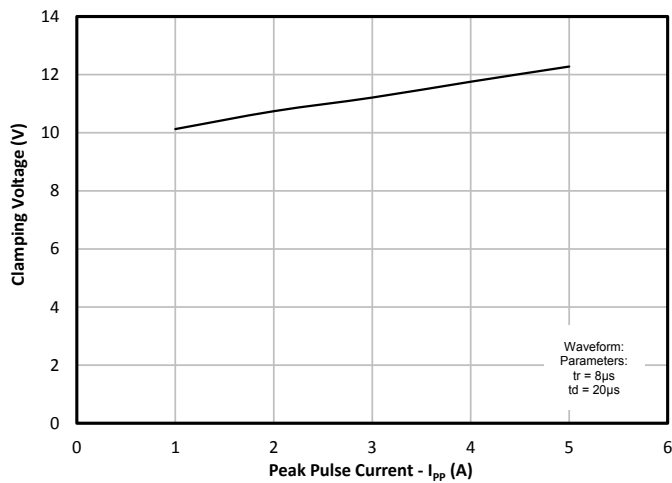
Non-Repetitive Peak Pulse Power



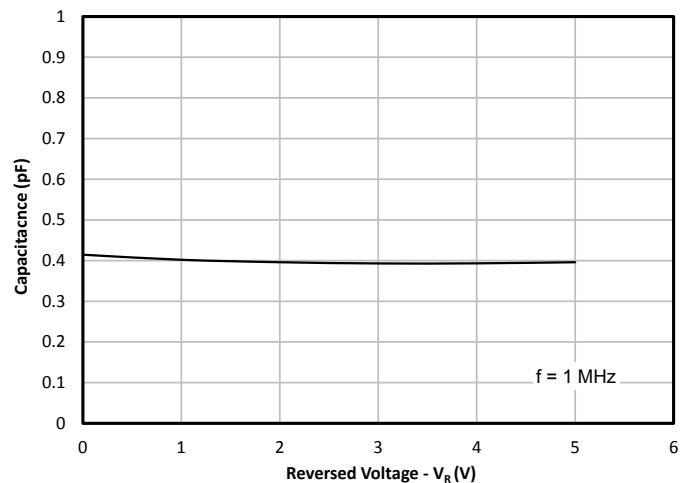
Power Derating Curve



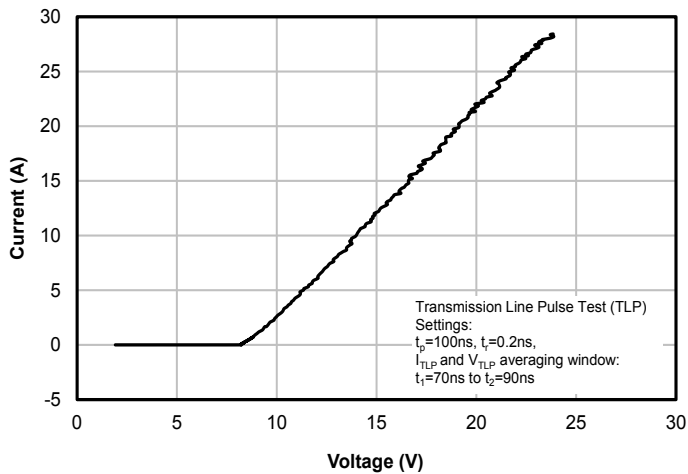
Clamping Voltage vs. Peak Pulse Current (Between any I/O and Ground)



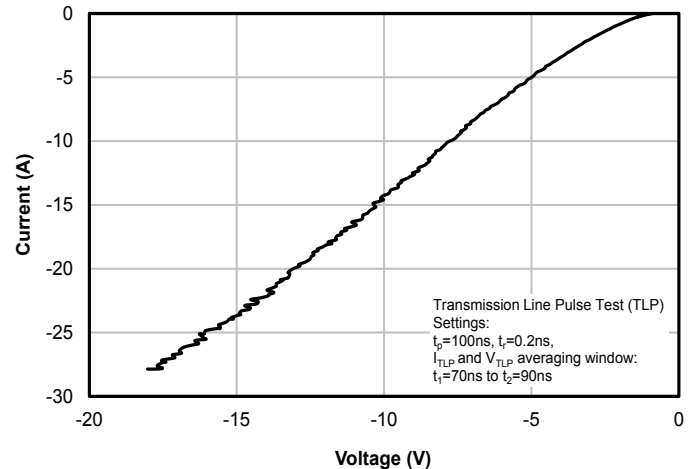
Junction Capacitance vs. Reverse Voltage (Between any I/O and Ground)



TLP Characteristic (Positive)

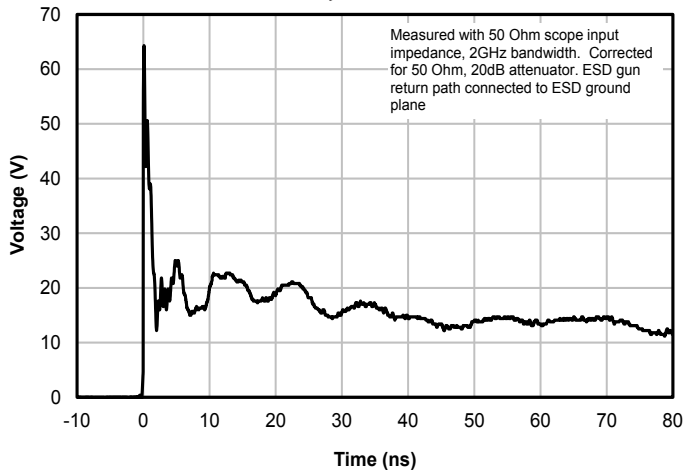


TLP Characteristic (Negative)

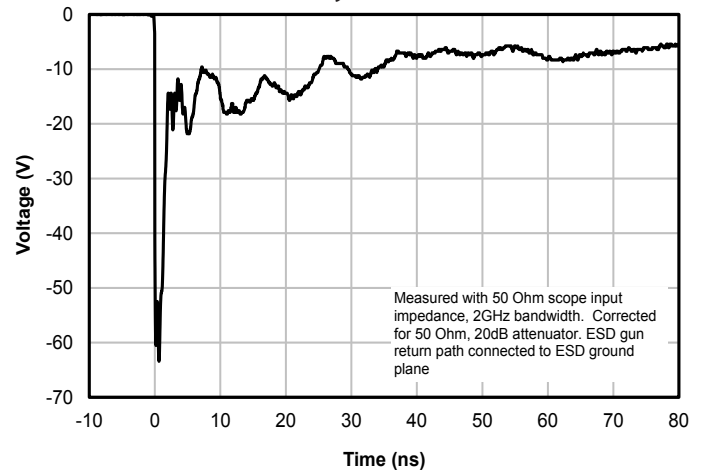


Typical Characteristics (Continued)

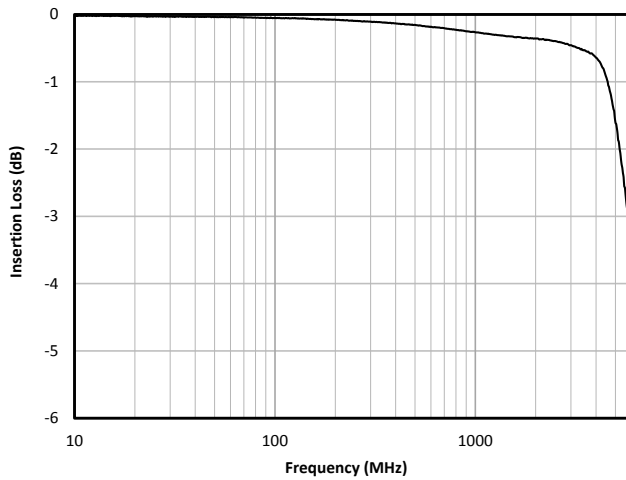
**ESD Clamping (+8kV Contact per IEC 614000-4-2)
(Between any I/O to Ground)**



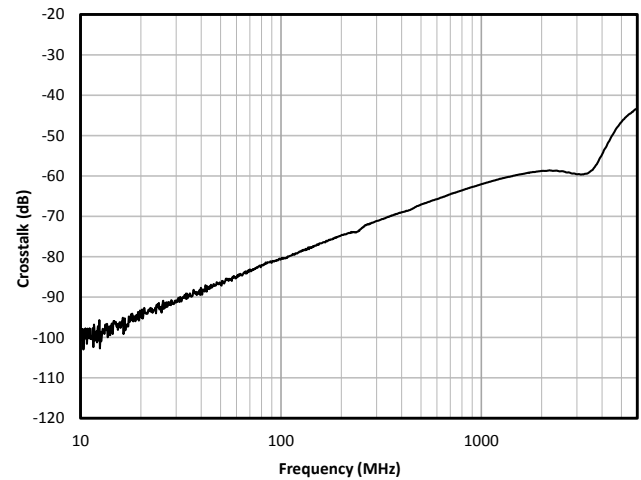
**ESD Clamping (-8kV Contact per IEC 614000-4-2)
(Between any I/O to Ground)**



Typical Insetion Loss S21



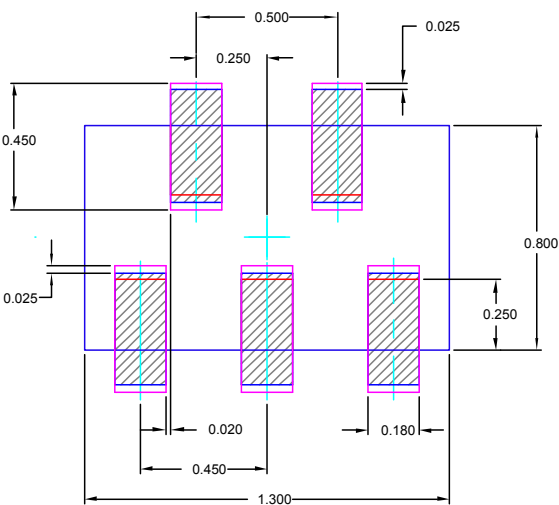
Analog Crosstalk



Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.



All Dimensions are in mm.

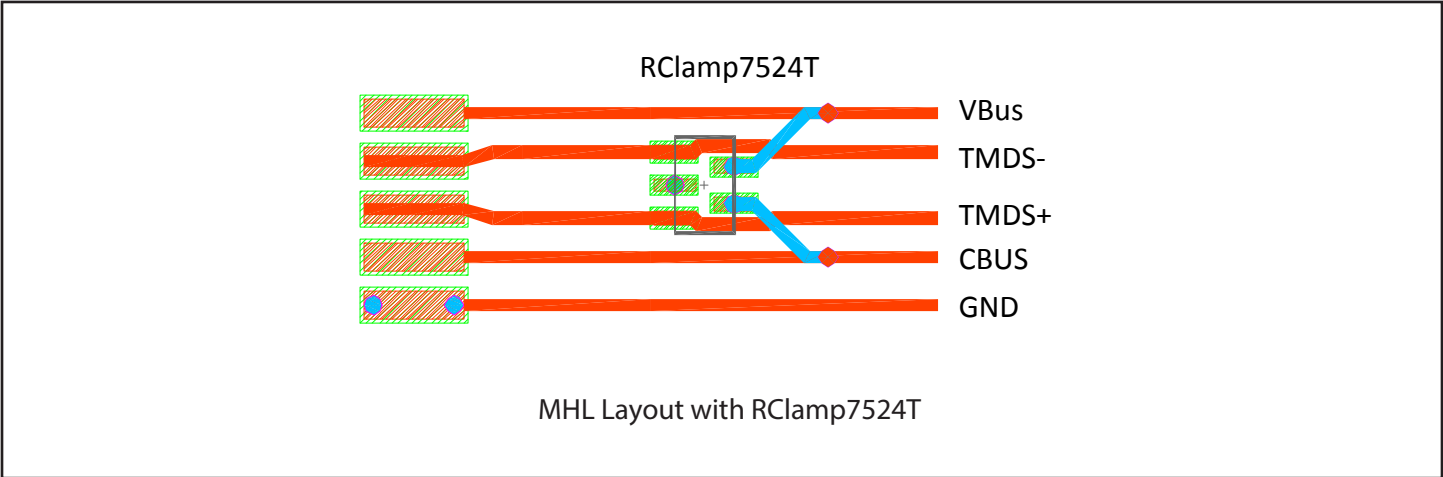
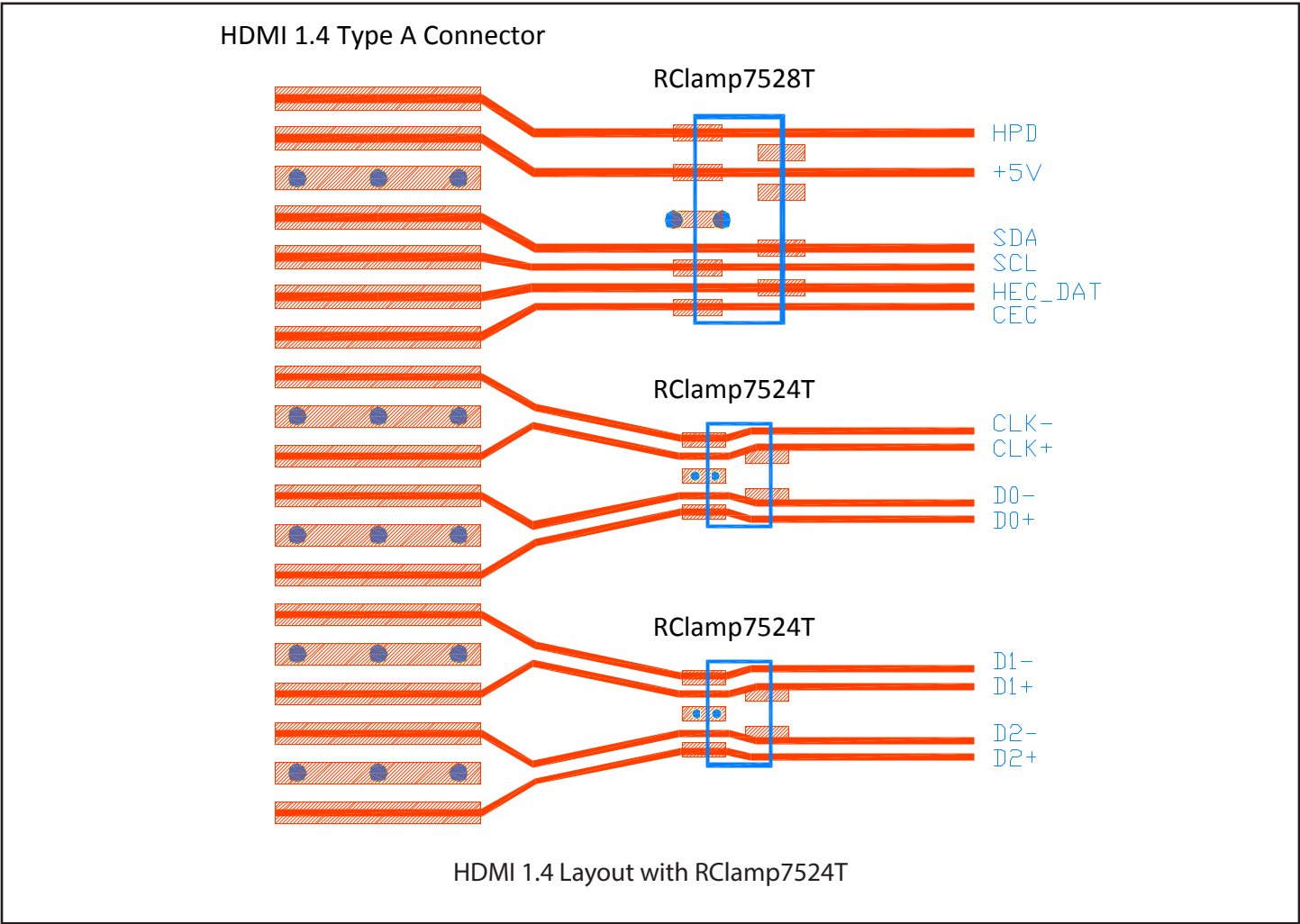
Land Pad. Stencil opening Component

Recommended Mounting Pattern

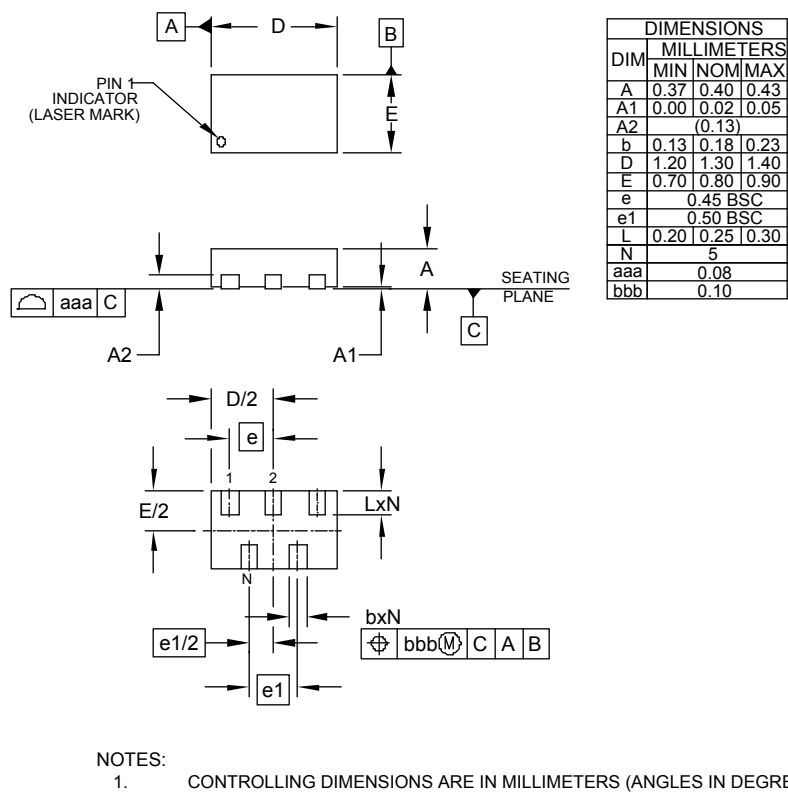
Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-polished
Aperture shape	Rectangular
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paster Type	Type 4 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP Or NiAu

Application Information

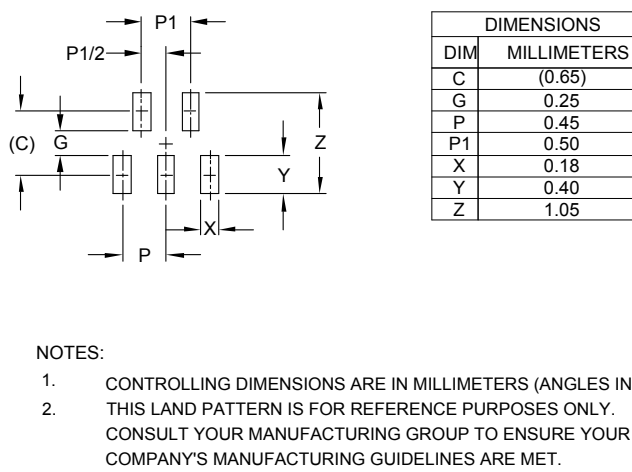
Application Information



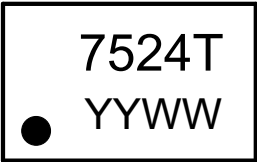
Outline Drawing - SLP1308N5T



Land Pattern - SLP1308N5T

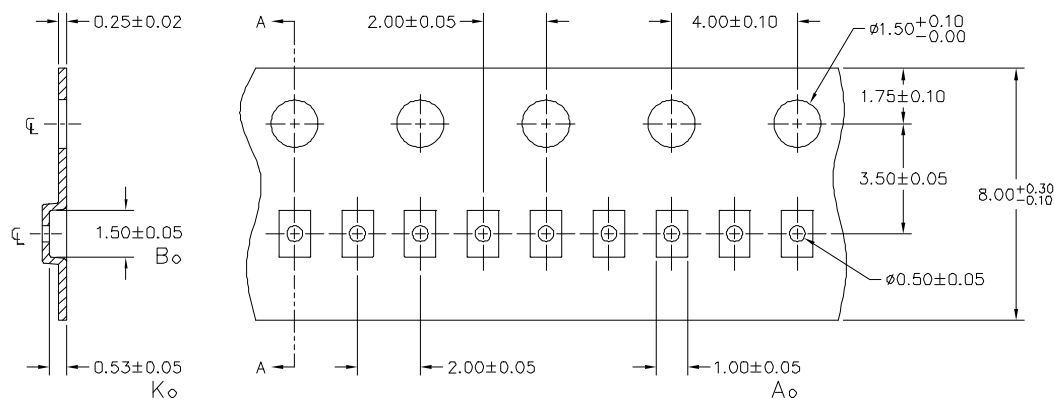


Marking Code



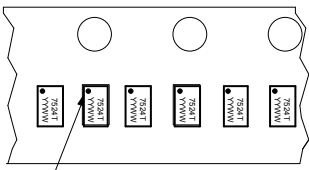
Note: YYWW = Date Code

Tape and Reel Specification



SECTION A-A

NOTE: ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp7524T.TNT	10,000	7"



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